



THE BOTTOM OF 2~3P

THE BOTTOM OF 4~30P

- NOTES:
- MATERIAL:
    - HOUSING: HALOGEN FREE PLASTIC, UL94V-0.
    - CONTACT: COPPER ALLOY
    - FITTING NAIL: COPPER ALLOY
  - CONTACT:
    - L: 50U" NICKEL OVERALL, 120U" MIN. LEAD-FREE (PURE TIN).
    - 1: 50U" NICKEL OVERALL, GOLD FLASH OVER ALL (1U" MIN).
    - N: 50U" NICKEL OVERALL, 120U" MIN. PURE TIN (MATT TIN) ALLOY.
    - C: 15U" GOLD ON CONTACT AND, GOLD FLASH SOLDER AREA.
    - B: 5U" GOLD ON CONTACT FOR LEAD FREE
    - T: 10U" GOLD ON CONTACT AND, GOLD FLASH SOLDER AREA.
  - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
  - SPEC. PLS. REFER TO PS-50281-XXXX-XXX
  - PART NUMBER

PCB PATTERN LAYOUT

P/N LEGEND

50281-XXX X X-XXX

NO OF CKT

PACKING

0: TAPE & REEL

1: TUBE PACKAGE

XXX	Housing Color	PACKING
001	Black	88266-XXXX-TRP
002	Natural	88266-XXXX-TRP
003	Black	88266-XXXX-U-TRP

PLATING

L: PURE TIN (LEAD FREE)

1: G/F ON OVERALL (LEAD FREE)

N: MATT TIN (LEAD FREE)

C: 15U" GOLD ON CONTACT

B: 5U" GOLD ON CONTACT FOR LEAD FREE

T: 10U" GOLD ON CONTACT

CKT	Dim A	Dim B	Dim D
2	1.25	6.10	CEN
3	2.50	7.35	CEN
4	3.75	8.60	2.50
5	5.00	9.85	3.75
6	6.25	11.10	5.00
7	7.50	12.35	6.25
8	8.75	13.60	7.50
9	10.00	14.85	8.75
10	11.25	16.10	10.00
11	12.50	17.35	11.25
12	13.75	18.60	12.50
14	16.25	21.10	15.00
15	17.50	22.35	16.25
16	18.75	23.60	17.50
18	21.25	26.10	20.00
20	23.75	28.60	22.50
22	26.25	31.10	25.00
24	28.75	33.60	27.50
25	30.00	34.85	28.75
26	31.25	36.10	30.00
28	33.75	38.60	32.50
30	36.25	41.10	35.00

QUALITY SYMBOLS	DRAWN BY Huang, Shun Sen	DATE 19/04/27	<b>ACES</b> ELECTRONICS	
MAJOR CRITICAL	CHECKED BY Lu, Jing Quan	DATE 19/04/27		
GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVED BY hsieh, fu yu	DATE 19/04/27	TITLE 1.25mm WTB LPF Header SMT R/A S/R Type	
.X ±0.5	UNITS mm	SCALE 8:1	SIZE A4	RFQ NO. X
.XX ±0.15	SCALE 8:1	SHEET NO. 1 OF 1	REV F	PART NO. SEE NOTES
.XXX ±0.1				DWG NO. 50281-XXXX-XXX
ANGLES ±2°				